



HDBNC-J-P-GN-ST-EM1



HDBNC-J-P-GN-ST-BH1



HDBNC-J-P-GN-RA-BH1



HDBNC-J-P-GN-ST-TH1

HDBNC SERIES

75 Ω HIGH DENSITY BNC JACKS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDBNC-TH, www.samtec.com?HDBNC-BH1 or www.samtec.com?HDBNC-EM

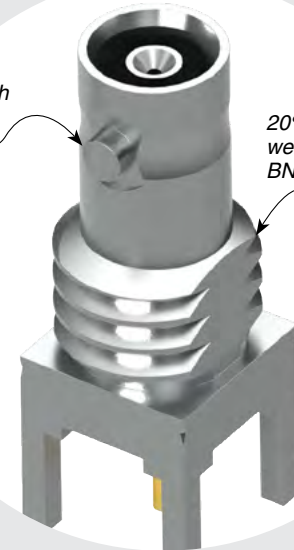
- Shell Material:**
Au plated Brass
- Contact Material:**
Copper Alloy
- Insulator Material:**
PTFE
- Impedance:**
75Ω ±2Ω
- Frequency Range:**
-EM & -TH: 0-12 GHz
-RA: 0-6 GHz
- V.S.W.R:**
1.45 max
(with optimized launch design)
- Working Voltage:**
330 Vrms max
- Dielectric Withstanding:**
1500 Vrms min
- Contact Resistance:**
Center Contact: 1.5mΩ max
Outer Contact: 0.4mΩ max
- Operating Temperature:**
-65 °C to +125 °C
- RoHS Compliant:**
Yes
- Lead-Free Solderable:**
Yes

Mates with:
RFB6T, RFB8T, RFA6T



Patented design and bayonet latch

20% reduction in weight of traditional BNCs

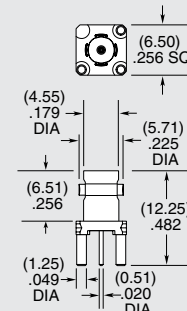
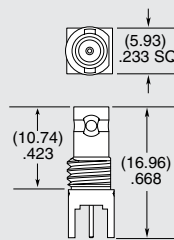
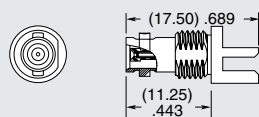
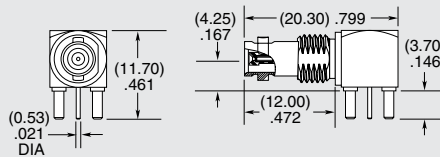


Extended performance of 12G for high density -EM & -TH terminations

EXTRACTION TOOL

- Hand tool for quickly installing/uninstalling Contact Samtec.

HDBNC	GENDER	TYPE	PLATING	ORIENTATION	TERMINATION
-J = Jack		-P = PCB Mount	-GN = 10μ" (0.25 μm) Gold contact, 100 μ" (2.54 μm) Nickel shell	-ST = Straight -RA = Right Angle	-BH1 = Through-hole -BH2 = Through-hole (2.36 mm) .093 Board (-RA only) -EM1 = Edge Mount (-ST only) -TH1 = Through-hole (-ST only)



Notes: Compatible with Amphenol's HD-BNC™

Designed to meet SMPTE 424M 12G-SDI specifications.